TIDA-00254 Test Results
March 2016

Accurate Point Cloud Generation for 3D Machine Vision Applications using DLP® Technology and Industrial Camera

About Test Results
This DLP technology based TI Design provides a complete solution for 3D scanning and point cloud generation. The point cloud data below was generated using the software include with this TI Design, which is based on the DLP Advanced Light Control SDK with a DLP® LightCrafter™ 4500 EVM and Point Grey Flea3 USB camera. The generated point cloud data was visualized using MeshLab.

Related Documentation From Texas Instruments
- DLPC350 Data Sheet: DLP Digital Controller for Portable Advanced Light Control, TI literature number DLPS029
- DLP4500 Data Sheet: DLP 0.45 WXGA Visible DMD, TI literature number DLPS028
- DLP4500NIR Data Sheet: DLP 0.45 WXGA Near-Infrared DMD, TI literature number DLPS032
- Application Note: Using DLP® Development Kits for 3D Optical Metrology Systems, TI literature number DLPA026
- Application Note: Using DLP® LightCrafter™ 4500 Triggers to Synchronize Cameras to Patterns, TI literature number DLPA036

If You Need Assistance
Refer to the DLP and MEMS TI E2E Community support forums

Calibration Results
This chapter provides test data from the TIDA-00254 software for camera and projector calibration module. When the camera and projector calibration parameters are found, the output is used to generate the system optical rays which ultimately allow line intersections to be calculated for point cloud generation.

To calibrate the system, the following procedure is used:

1. From main menu of software, select “1: Generate camera calibration board and enter feature measurements” and follow instructions
   a. Note: Measure the height of one square on the calibration board in the desired units of the point cloud
2. From main menu of software, select “4: Calibrate camera” and follow instructions.
3. From main menu of software, select “5: Calibrate system” and follow instructions.

The following images show the camera captures of the printed calibration board and projected calibration board after removing the printed calibration board from the projected.

Figure 1 Camera calibration board measurement

Figure 2 Printed calibration board and projected calibration board position 1
**Figure 3** Printed calibration board and projected calibration board position 2

**Figure 4** Printed calibration board and projected calibration board position 3

**Figure 5** Printed calibration board and projected calibration board position 4
**Figure 6** Printed calibration board and projected calibration board position 5

**Figure 7** Printed calibration board and projected calibration board position 6

**Figure 8** Printed calibration board and projected calibration board position 7
Figure 9 Printed calibration board and projected calibration board position 8

Figure 10 Printed calibration board and projected calibration board position 9

Figure 11 Printed calibration board and projected calibration board position 10
The following images should the calibration XML files generated for the camera and projector.

```xml
<?xml version="1.0"?>
<opencv_storage>
  <DLP_CALIBRATION_DATA>
    <calibration_complete>1</calibration_complete>
    <camera_calibration>1</camera_calibration>
    <image_columns>1280</image_columns>
    <image_rows>1024</image_rows>
    <model_columns>1280</model_columns>
    <model_rows>1024</model_rows>
    <reprojection_error>4.208255580520471e-001</reprojection_error>
    <intrinsic_type_id>opencv_matrix</intrinsic_type_id>
      <rows>3</rows>
      <cols>3</cols>
      <data>1.65664273622487740e+003 0.66745403364774097e+002 1.6626729442650779e+003 4.5049026481526446e+002 0.0 0.0 1.0</data>
    </intrinsic>
    <distortion_type_id>opencv_matrix</distortion_type_id>
      <rows>5</rows>
      <cols>1</cols>
      <data>1.5313122964505867e-001 1.4106990980281424e-001 -7.6412243701293399e-003 3.7139263424160273e-003 1.179087742774914e+000</data>
    </distortion>
    <extrinsic_type_id>opencv_matrix</extrinsic_type_id>
      <rows>2</rows>
      <cols>3</cols>
      <data>2.5421149198926610e-001 -2.483260776153297e-002 1.021203984677576e-002 -4.775123076591871e+000 -3.310100638266598e+000 2.1445074696632794e+001</data>
    </extrinsic>
  </DLP_CALIBRATION_DATA>
</opencv_storage>
```

**Figure 12** Camera calibration XML output file

```xml
<?xml version="1.0"?>
<opencv_storage>
  <DLP_CALIBRATION_DATA>
    <calibration_complete>1</calibration_complete>
    <camera_calibration>1</camera_calibration>
    <image_columns>1280</image_columns>
    <image_rows>1024</image_rows>
    <model_columns>912</model_columns>
    <model_rows>1140</model_rows>
    <reprojection_error>2.0780651604929285e-001</reprojection_error>
    <intrinsic_type_id>opencv_matrix</intrinsic_type_id>
      <rows>3</rows>
      <cols>3</cols>
      <data>1.1099161301256515e+003 4.4295614686914325e+002 0.1.1099161301256515e+003 3.827435073128078e+002 0.0 0.0 1.0</data>
    </intrinsic>
    <distortion_type_id>opencv_matrix</distortion_type_id>
      <rows>5</rows>
      <cols>1</cols>
      <data>-4.15301552151959585e-004 -4.15301552151959585e-004 4.1370577504474170e-002</data>
    </distortion>
    <extrinsic_type_id>opencv_matrix</extrinsic_type_id>
      <rows>2</rows>
      <cols>3</cols>
      <data>2.8247810288424102e-003 -4.7425102105252401e-002 1.0466032537895450e-002 -4.2521674523310915e+000 -7.939540109262069e+000 1.949131380134375e+001</data>
    </extrinsic>
  </DLP_CALIBRATION_DATA>
</opencv_storage>
```

**Figure 13** Projector calibration XML output file
**Generated Point Cloud**

This chapter provides test data from the TIDA-00254 software for structured light pattern decoding and point cloud generation. The structured light module generates patterns to determine which projector rays are intersecting with the scanned object and the geometry module finds the intersection between the projector and camera optical rays to generate a depth-map and point-cloud.

To calibrate the system, the following procedure is used:

1. Calibrate the camera and system
2. From main menu of software, select “3: Prepare system for calibration and scanning”
3. From main menu of software, select “8: Perform scan (vertical and horizontal patterns)”

The following images show the camera captures of the projected structured light patterns:

![Figure 14](image1.png)  ![Figure 15](image2.png)

**Figure 14** Non-inverted and inverted vertical gray code pattern 1 capture

**Figure 15** Non-inverted and inverted vertical gray code pattern 2 capture
Figure 16 Non-inverted and inverted vertical gray code pattern 3 capture

Figure 17 Non-inverted and inverted vertical gray code pattern 4 capture

Figure 18 Non-inverted and inverted vertical gray code pattern 5 capture
**Figure 19** Non-inverted and inverted vertical gray code pattern 6 capture

**Figure 20** Non-inverted and inverted vertical gray code pattern 7 capture

**Figure 21** Non-inverted and inverted vertical gray code pattern 8 capture
Figure 22 Non-inverted and inverted vertical gray code pattern 9 capture

Figure 23 Non-inverted and inverted horizontal gray code pattern 1 capture
Figure 24 Non-inverted and inverted horizontal gray code pattern 2 capture

Figure 25 Non-inverted and inverted horizontal gray code pattern 3 capture

Figure 26 Non-inverted and inverted horizontal gray code pattern 4 capture
Figure 27 Non-inverted and inverted horizontal gray code pattern 5 capture

Figure 28 Non-inverted and inverted horizontal gray code pattern 6 capture

Figure 29 Non-inverted and inverted horizontal gray code pattern 7 capture
Figure 30 Non-inverted and inverted horizontal gray code pattern 8 capture

Figure 31 Non-inverted and inverted horizontal gray code pattern 9 capture

The following images show the depth-map and various views of the generated point cloud:
Figure 32 Depth-map of object from 3D scan
Figure 33 Front view of point-cloud from 3D scan
Figure 34 Side view of point-cloud from 3D scan
Figure 35 Top view of point-cloud from 3D scan
Figure 36 Isometric view of point-cloud from 3D scan
**Generated Point Cloud from Hybrid Three Phase Scan**

This chapter provides test data from the DLP ALC SDK for structured light pattern decoding and point cloud generation. In this test case a three-phase hybrid scan using horizontal patterns is demonstrated.

To calibrate the system, the following procedure is used:

1. Calibrate the camera and system
2. From main menu of software, select “3: Prepare system for calibration and scanning”
3. From main menu of software, select “7: Perform scan (horizontal patterns only)”

The following images show the camera captures of the projected structured light patterns:

![Figure 37 Three phase patterns](image1)

![Figure 38 Non-inverted and inverted horizontal gray code pattern 1 capture](image2)
Figure 39 Non-inverted and inverted horizontal gray code pattern 2 capture

Figure 40 Non-inverted and inverted horizontal gray code pattern 3 capture

Figure 41 Non-inverted and inverted horizontal gray code pattern 4 capture
Figure 42 Non-inverted and inverted horizontal gray code pattern 5 capture

Figure 43 Non-inverted and inverted horizontal gray code pattern 6 capture

Figure 44 Non-inverted and inverted horizontal gray code pattern 7 capture
Figure 45 Non-inverted and inverted horizontal gray code pattern 8 capture

Figure 46 Non-inverted and inverted horizontal gray code pattern 9 capture
Figure 47 Bottom view of point cloud

Figure 48 Isometric view of point cloud
Figure 49 Rear view of point cloud
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